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Front Matter: Volume 8066

, "Front Matter: Volume 8066," Proc. SPIE 8066, Smart Sensors, Actuators, and MEMS V, 806601 (1 June 2011); doi: 10.1117/12.899482

SPIE.

Event: SPIE Microtechnologies, 2011, Prague, Czech Republic

PROCEEDINGS OF SPIE

Smart Sensors, Actuators, and MEMS V

**Ulrich Schmid
José Luis Sánchez-Rojas
Monika Leester-Schaedel**
Editors

**18–20 April 2011
Prague, Czech Republic**

Sponsored and Published by
SPIE

Volume 8066

Proceedings of SPIE, 0277-786X, v. 8066

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Author(s), "Title of Paper," in *Smart Sensors, Actuators, and MEMS V*, edited by Ulrich Schmid, José Luis Sánchez-Rojas, Monika Leester-Schaedel, Proceedings of SPIE Vol. 8066 (SPIE, Bellingham, WA, 2011) Article CID Number.

ISSN 0277-786X

ISBN 9780819486554

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time)· Fax +1 360 647 1445

SPIE.org

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Printed in the United States of America.

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Introduction

The Smart Sensors, Actuators, and MEMS conference took place in Prague, Czech Republic 18–20 April 2011. Almost 100 contributions from Europe, America, and Asia were accepted and grouped into 9 sessions including a poster session. The interdisciplinary spirit of the event was displayed by a wide range of topics based on the latest results achieved in the research and development areas of precision engineering and MEMS. Therefore sessions focused on material and fabrication aspects, on micromachined sensors and actuators for the determination of biological, physical, and chemical quantities, as well as on reliability issues. Moreover, optical and RF MEMS were presented and more application-oriented topics such as energy scavengers, microfluidic systems, and low power management systems were discussed. This broad range of topics, plus researchers coming from academia and industry with their specific backgrounds, created a very stimulating atmosphere for the exchange of new ideas.

Besides the high quality of the oral and poster presentations, I would like to highlight the three invited talks: Omar Elmazria from CNRS-Nancy University, France, on “Materials and device-related aspects for the high temperature operation of SAW sensor elements” (806602); by Andreu Llobera, Centro Nacional de Microelectrónica, Spain, on photonic microreactors and their application in real-time cell screening (80660D); and last, but not least, by Gunilla Wingqvist, Linköping University, Sweden, on piezoelectric sensor elements operated in liquid media and excited by pure or modified aluminium nitride thin films (80660U).

I would like to thank all participants for their individual contributions which made the conference a successful event in the international conference calendar.

Special thanks go to José Feliciano López, Gerhard Krötz, and Thomas Becker for organising the symposium, the SPIE staff, and to my cochairs José Luis Sánchez de Rojas Aldavero (Univ. Castilla-La Mancha, Ciudad Real, Spain) and Monika Leester-Schaedel (Technische Universität Braunschweig, Germany). Finally I would like to thank the programme committee for doing the reviews and acting partly as session chairs.

Ulrich Schmid
José Luis Sánchez-Rojas
Monika Leester-Schaedel